



PCN# : P523AAB
Issue Date : Mar. 19, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jun. 17, 2015

Expected First Date Code of Changed Product :1522

Description of Change (From) :

5-inch wafer fabrication of wafer business products in Fairchild in Bucheon, South Korea


Description of Change (To) :

6 & 8-inch wafer fabrication of wafer business products in Fairchild in Bucheon, South Korea

Reason for Change:

Fairchild Semiconductor is increasing wafer fabrication capacity by qualifying 6,8-inch wafer fabrication line at Fairchild Semiconductor Bucheon Korea. Quality and reliability remain at the highest standards already demonstrated within Fairchild's existing products.

The reliability qualification results used to qualify the 6,8-inch wafer fabrication line are summarized below. Design, die size and layout of the affected products will remain unchanged. There are no changes in the datasheet or electrical performance.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history. To see the entire list of affected parts, please click the following link: 

Qualification Plan	Device	Package	Process	No. of Lots
Q20140052	FGH60N60SMD_F085	TO247	Hyperfast	3

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	480V,175C	JESD22-A108	1000hrs	0/231
High Humidity High Temp. Reverse Bias(H3TRB)	85%RH, 85C,100V	JESD22-A101B	1000hrs	0/231
Autoclave	100%RH, 121C	JESD22-A102	96hrs	0/231
Temperature Cycle	-55C,150C	JESD22-A104	1000cycles	0/231
Power Cycle	, On/Off=2.0min, Delta Tj=100C	MIL-STD-750 M1037	6000cycles	0/77
High Temperature Storage Life	175C	JESD22-A103	1000hrs	0/231
Destructive Physical Analysis	Per AEC-Q101-004		N/A	0/21

Qualification Plan	Device	Package	Process	No. of Lots
Q20140047	FGH75T65UPD_F085	TO247	Stealth	3

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	520V,175C	JESD22-A108	1000hrs	0/231
High Humidity High Temp. Reverse Bias(H3TRB)	85%RH, 85C,100V	JESD22-A101B	1000hrs	0/231
Autoclave	100%RH, 121C	JESD22-A102	96hrs	0/231
Temperature Cycle	-55C,150C	JESD22-A104	1000cycles	0/231
Power Cycle	, On/Off=2.0min, Delta Tj=100C	MIL-STD-750 M1037	6000cycles	0/77
High Temperature Storage Life	175C	JESD22-A103	1000hrs	0/231
Destructive Physical Analysis	Per AEC-Q101-004		N/A	0/21

Qualification Plan	Device	Package	Process	No. of Lots
Q20140051	RURG8060_F085	TO247	Ultrafast	3

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	480V,175C	JESD22-A108	1000hrs	0/231
High Humidity High Temp. Reverse Bias(H3TRB)	85%RH, 85C,100V	JESD22-A101B	1000hrs	0/231
Autoclave	100%RH, 121C	JESD22-A102	96hrs	0/231
Temperature Cycle	-55C,150C	JESD22-A104	1000cycles	0/231
Power Cycle	, On/Off=2.0min, Delta Tj=100C	MIL-STD-750 M1037	6000cycles	0/77
High Temperature Storage Life	175C	JESD22-A103	1000hrs	0/231
Destructive Physical Analysis	Per AEC-Q101-004		N/A	0/21

Qualification Plan	Device	Package	Process	No. of Lots
Q20140141	FQB34P10TM_F085	D2PAK	Q-FET P-ch	3

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	175C, 100V	JESD22-A108	1000hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, 42V	JESD22-A110	96hrs	0/231
Autoclave	100%RH, 121C	JESD22-A102	96hrs	0/231
Power Cycle	Delta 100CC, 3.5 Min On/Off	JESD22-A122	8572cycles	0/231
Temperature Cycle	-55C ,150C	JESD22-A104	1000cycles	0/231
Destructive Physical Analysis	Per AEC-Q101-004		NA	0/21

Qualification Plan	Device	Package	Process	No. of Lots
Q20140055	FGD3N60LSDTM_SB82154	DPAK	PT-PIGBT	3

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, 480V	JESD22-A108	1000hrs	0/231
High Temperature Gate Bias	150C, 25V	JESD22-A108	1000hrs	0/231
High Humidity High Temp. Reverse Bias(H3TRB)	85%RH, 85C,100V	JESD22-A101B	1000hrs	0/231
Autoclave	100%RH, 121C	JESD22-A102	96hrs	0/231
Temperature Cycle	-55C ,150C	JESD22-A104	1000cycles	0/230
Power Cycle	Delta 100CC, 2 Min On/Off	JESD22-A122	6000cycles	0/77
High Temperature Storage Life	150C	JESD22-A103	1000hrs	0/231
Destructive Physical Analysis	Per AEC-Q101-004		NA	0/21

Qualification Plan	Device	Package	Process	No. of Lots
QP1311001	FGH40N120ANTU	TO247	NPT-PIGBT	3

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, 960V	JESD22-A108	1000hrs	0/231
High Temperature Gate Bias	150C, 25V	JESD22-A108	1000hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, 42V	JESD22-A110	96hrs	0/229
Temperature Cycle	-65C ,150C	JESD22-A104	1000cycles	0/231
Power Cycle	Delta 100CC, 2 Min On/Off	JESD22-A122	6000cycles	0/231
High Temperature Storage Life	150C	JESD22-A103	1000hrs	0/231